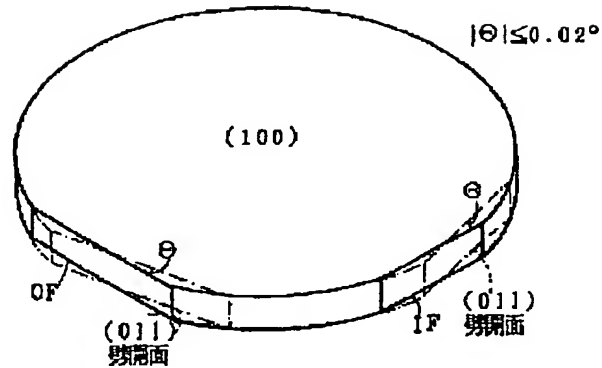


Patent Abstracts of Japan

TITLE : III-V COMPOUND SEMICONDUCTOR
WAFER AND ITS MACHINING
METHOD



COPYRIGHT: (C)1995,JPO